



## Material Content Data Sheet



<b>Sales Product Name</b>		ESD208-B1-02ELS E6327		<b>Issued</b>		19. July 2018		
<b>MA#</b>		MA001140022						
<b>Package</b>		PG-TSSLP-2-3		<b>Weight*</b>		0.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.17		1707	
	noble metal	gold	7440-57-5	0.001	0.66		6615	
	inorganic material	silicon	7440-21-3	0.010	4.90	5.73	49028	57350
leadframe	non noble metal	nickel	7440-02-0	0.108	52.90	52.90	528830	528830
wire	non noble metal	copper	7440-50-8	0.002	0.75	0.75	7549	7549
encapsulation	organic material	carbon black	1333-86-4	0.000	0.19		1942	
	plastics	epoxy resin	-	0.012	5.63		56264	
	inorganic material	silicondioxide	60676-86-0	0.067	32.98	38.80	329816	388022
leadfinish	noble metal	gold	7440-57-5	0.004	1.80	1.80	18044	18044
plating	noble metal	palladium	7440-05-3	0.000	0.01		78	
	noble metal	gold	7440-57-5	0.000	0.01	0.02	127	205
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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